

SOT905-1

HVQFN24, plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 3 mm x 3 mm x 0.85 mm

11 December 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN24
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	31-3-2006
Manufacturer package code	SOT905-1

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	-	-	0.85	1	mm
A ₂	package height	-	-	0.85	-	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	24	-	A/A



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2. Package outline

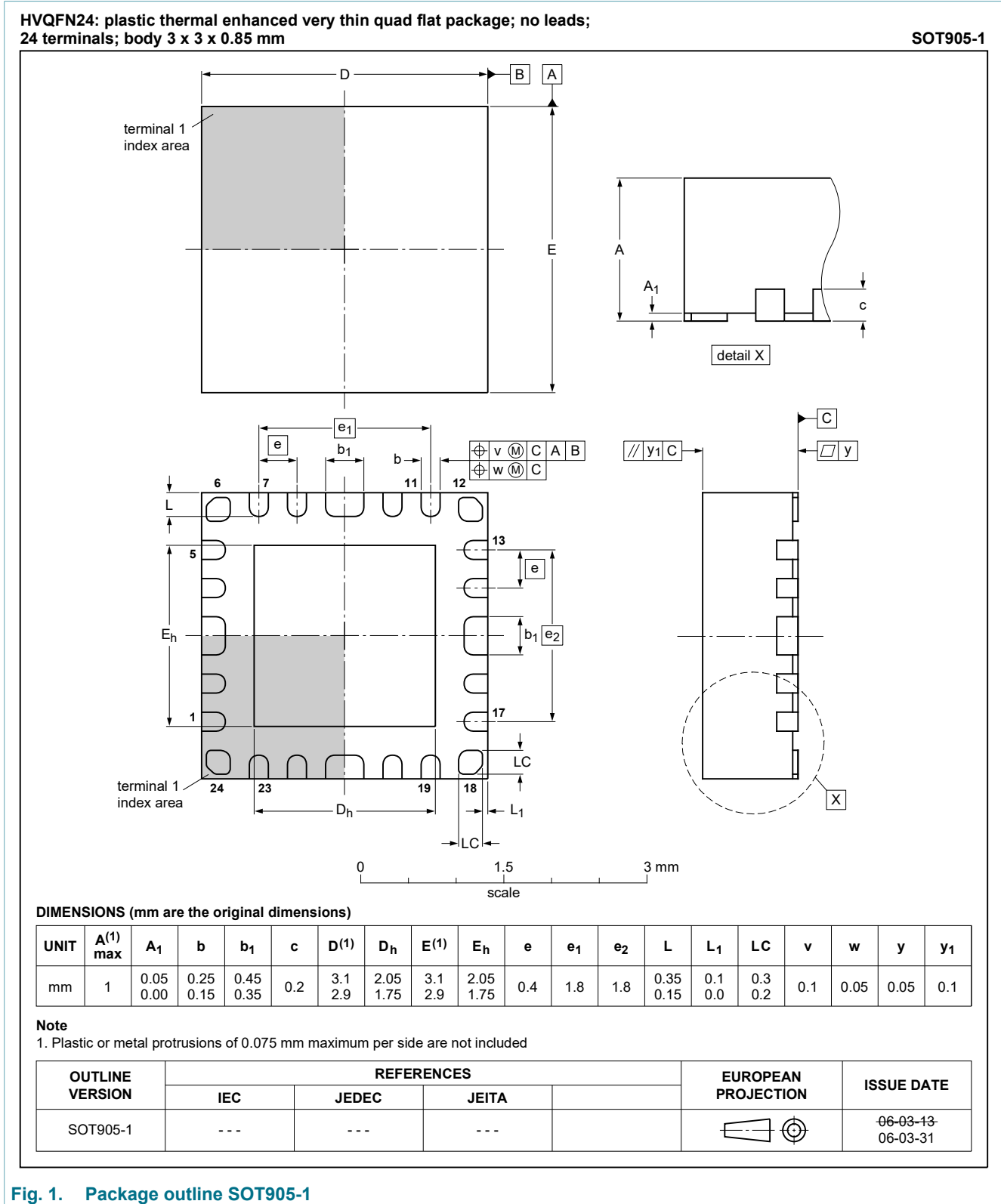


Fig. 1. Package outline SOT905-1

HVQFN24, plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 3 mm x 3 mm x 0.85 mm

3. Soldering

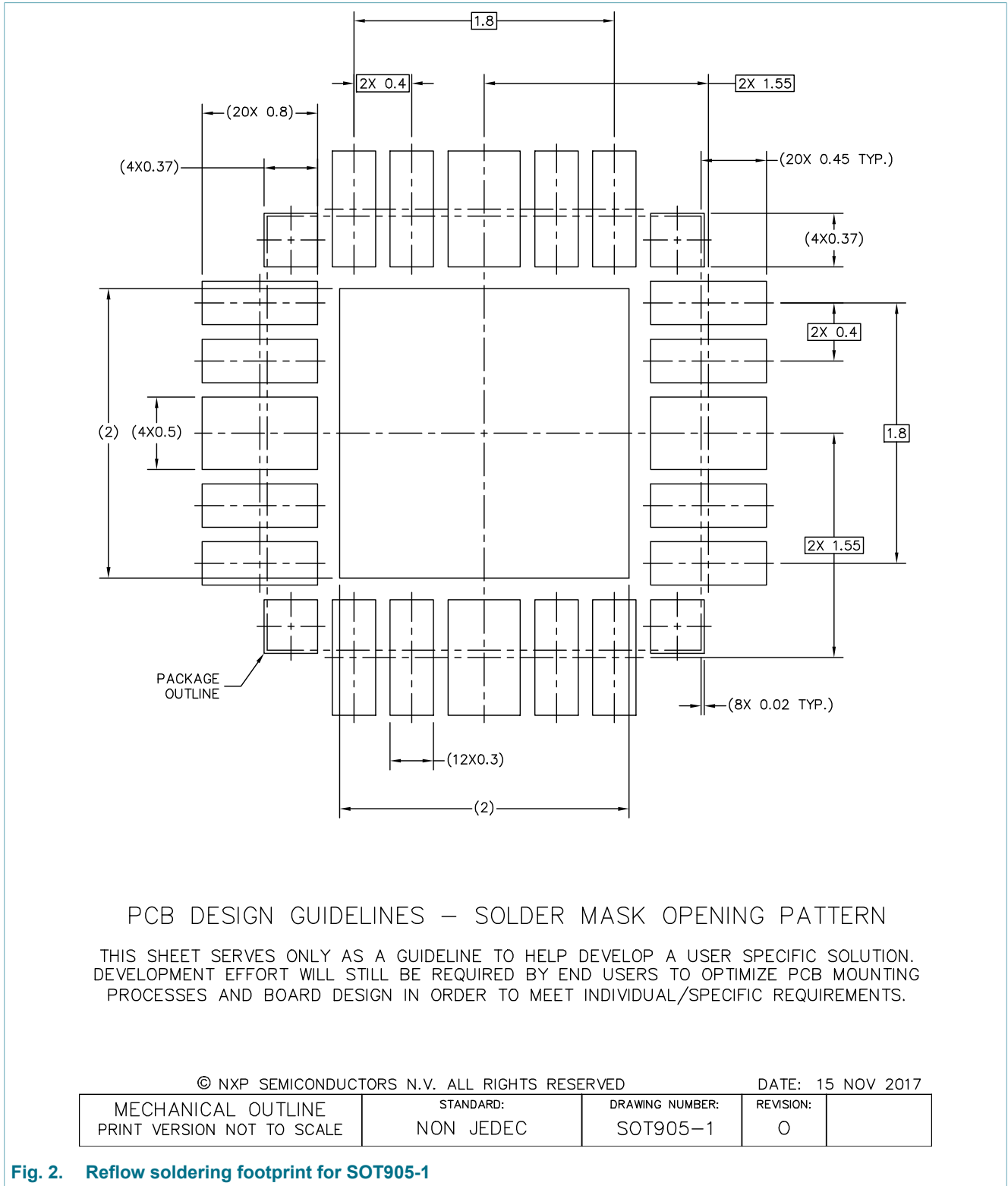
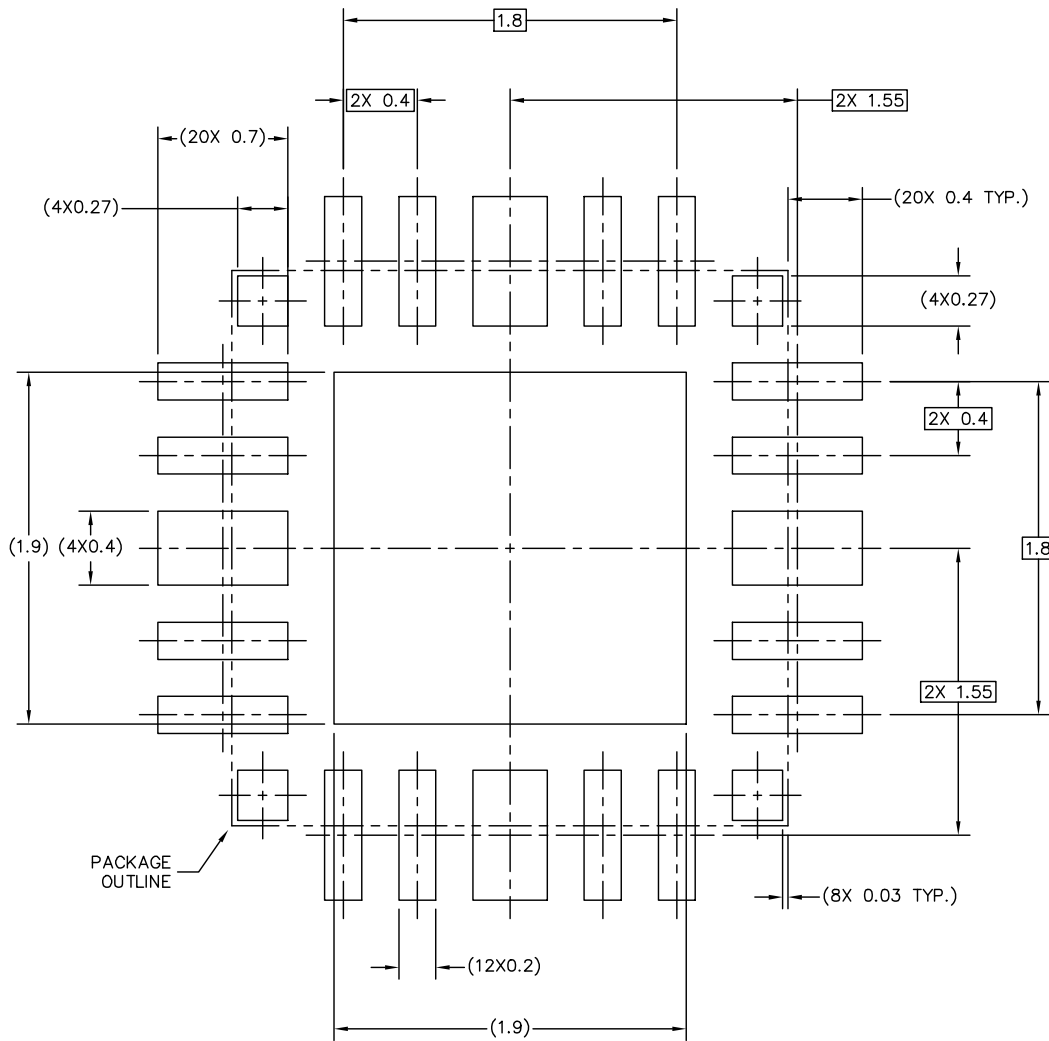


Fig. 2. Reflow soldering footprint for SOT905-1

HVQFN24, plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 3 mm x 3 mm x 0.85 mm



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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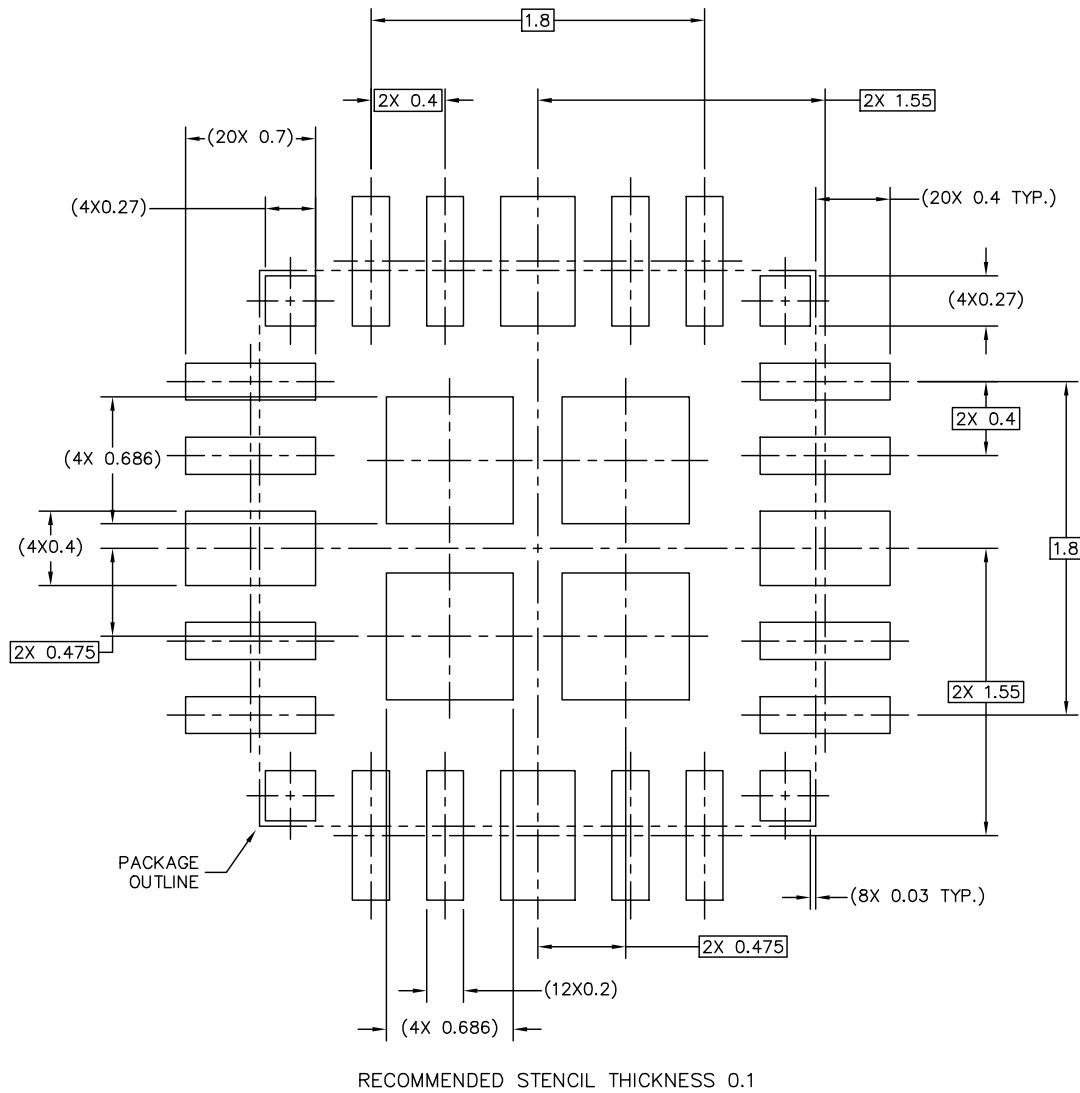
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Fig. 3. Reflow soldering footprint part2 for HVQFN24 (SOT905-1)

HVQFN24, plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 3 mm x 3 mm x 0.85 mm



PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Fig. 4. Reflow soldering footprint part3 for HVQFN24 (SOT905-1)

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4. Legal information

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Date of release: 11 December 2017
